CLAIMS

1. A semiconductor package heat generation simulation unit for checking heat distribution of a burn-in board, the unit comprising:

a circuit board including input/output terminals each corresponding to a conductive part of a socket of the burn-in board, and a power terminal and a signal terminal, connected to the input/output terminals;

a heater configured to generate heat by power input through the power terminal and including an opening exposing the signal terminal; and

a temperature sensor disposed in the opening while connected to the signal terminal and configured to measure a temperature of heat generated by the heater and output temperature information on the temperature through the signal terminal.

2. The unit of claim 1, further comprising a molding coupled to the circuit board while surrounding the heater and the temperature sensor.

3. The unit of claim 1, wherein the circuit board has a size corresponding to that of a semiconductor package that the socket is configured to receive.

4. The unit of claim 1, wherein the heater includes a surface heating element having a size corresponding to that of the circuit board.

5. A method for acquiring heat distribution of a burn-in board, the method comprising:

disposing the semiconductor package heat generation simulation unit according to claim 1 in a socket of the burn-in board;

supplying power to the heater through the socket, the input/output terminals, and the power terminal; and

receiving temperature information on a temperature measured by the temperature sensor based on heat generated by the heater through the signal terminal, the input/output terminals, and the socket.

6. The method of claim 5, further comprising outputting the temperature information on a screen for each socket of the burn-in board.